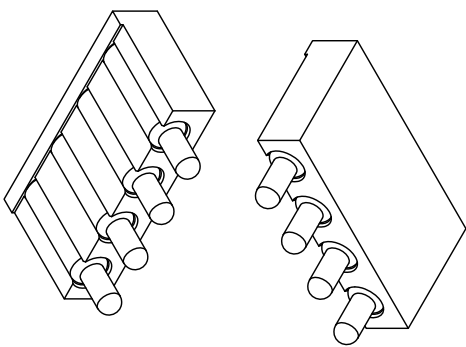
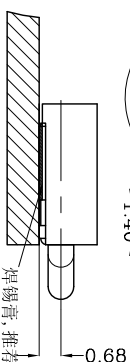
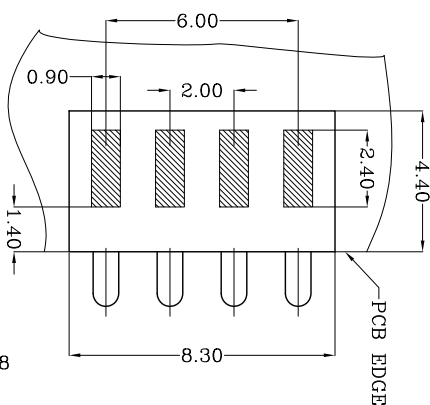


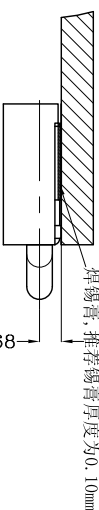
TOP-LINK



Application status 1

IMPORTANT: The recommended thickness of solder paste is 0.10mm

焊锡膏, 推荐锡膏厚度为 0.10mm



Application status 2
Recommended PCB Layout & Application

1)Body: Min 0.1um Gold plating over min. 1.4um Nickel plating
(Body: 鍍金0.1um Min 鍍底1.4um Min)

2)Plunger: Min 0.4um Gold plating over min. 1.4um Nickel plating
(Plunger: 镀金0.4um Min 镍底1.4um Min)

3 Mechanical:

Spring force: Min 0.2N with 0.3mm stroke
1.1 +0.30N/−0.20N with 1.0mm stroke.

Durability(寿命): 10,000 cycle min.

	變更材質		2010/05/12
	改Body結構		2007/12/04
LTR	REVISION RECORD	APVD	DATE

DIMENSIONS IN MM TOLERANCES UNLESS OTHER SPECIFIED		MATL	HT TR	FIN
0 = ±		DWN	APVD	Top-Link Electronics Ltd
0.0 = ±0.10		Qln		
0.00 = ±		CHK	REL	
0.0000 = ±				
ANGLE: ±1°				
SURF TEXTURE: 32/ V		NAME		
REMOVE BURRS, BREAK SHARP EDGES R0.05 MAX DO NOT SCALE PRINT		BATTERY POGO CONNECTOR 4 POSITIONS RIGHT ANGLE PGC-1.36-6.1-RA-4P-2.0PH		
SCALE	A4	DWG NO.	SHEET	REV
1:1		C-1000001	1 OF 1	E

1000001-4
PART NUMBER